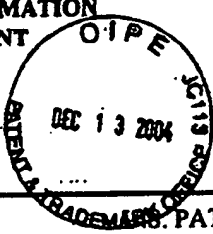





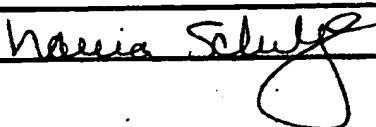


FORM PTO -1449				ATTY DOCKET NO.: ASC-23DVC2					
SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT				APPLICANT(S): Fitzgerald					
				SERIAL NO.: 10/022,689					
				FILING DATE: December 17, 2001					
				GROUP: 2813					
U.S. PATENT DOCUMENTS									
EXAM. INTT.		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE		
<i>RI</i>	A121	4,969,031	11/06/1990	Kobayashi <i>et al.</i>	—	—			
<i>RI</i>	A122	5,240,876	08/31/1993	Gaul <i>et al.</i>	—	—			
<i>RI</i>	A123	5,548,128	08/20/1996	Soref <i>et al.</i>	—	—			
<i>RI</i>	A124	5,572,043	11/05/1996	Shimizu <i>et al.</i>	—	—			
<i>RI</i>	A125	5,607,876	03/04/1997	Bitgelsen <i>et al.</i>	—	—			
<i>RI</i>	A126	6,352,909	03/05/2002	Usenko	—	—	05/26/2000		
<i>RI</i>	A127	6,372,593	04/16/2002	Hattori <i>et al.</i>	—	—	07/19/2000		
<i>RI</i>	A128	6,489,639	12/03/2002	Hoke <i>et al.</i>	—	—	05/24/2000		
<i>RI</i>	A129	6,524,935	02/25/2003	Canaperi <i>et al.</i>	—	—	09/29/2000		
<i>RI</i>	A130	6,646,322	11/11/2003	Fitzgerald	—	—	07/16/2001		
<i>RI</i>	A131	6,677,192	01/13/2004	Fitzgerald	—	—	07/16/2001		
<i>RI</i>	A132	6,703,688	03/09/2004	Fitzgerald	—	—	07/16/2001		
<i>RI</i>	A133	6,750,130	06/15/2004	Fitzgerald	—	—	01/07/2001		
FOREIGN PATENT DOCUMENTS									
EXAM. INTT.		DOCUMENT NUMBER	DATE	COUNTRY CODE	CLASS	SUB CLASS	FILING DATE	ABSTRACT ONLY	ENGLISH LANG (Y/N)
<i>RI</i>	B40	61-141116	06/28/1986	JP	—	—			Y (abstract only)
<i>RI</i>	B41	2-210816	08/22/1990	JP	—	—			Y (abstract only)
<i>RI</i>	B42	3-036717	02/18/1991	JP	—	—			Y
OTHER ART, JOURNAL ARTICLES									
EXAM. INTT.	OTHER DOCUMENTS: (Including Author, Title, Date, Relevant Pages, Place of Publication)								
<i>RI</i>	C95	Godbey <i>et al.</i> , (1990) "Fabrication of Bond and Etch-Back Silicon Insulator Using a Strained $\text{Si}_0.7\text{Ge}_{0.3}$ Layer as an Etch Stop," <i>Journal of the Electrical Society</i> , Vol. 137, No. 10 (October 1990) pp. 3219-3223.							
<i>RI</i>	C96	Grillot <i>et al.</i> , "Acceptor diffusion and segregation in $(\text{Al}_x\text{Ga}_{1-x})_0.5\text{In}_{0.5}\text{P}$ heterostructures," <i>Journal of Applied Physics</i> , Vol. 91, No. 8 (2002), pp. 4891-4899.							
EXAMINER		<i>Wesley Selig</i>			DATE CONSIDERED		3/3/05		

449		ATTY DOCKET NO.: ASC-23DVC2						
SUPPLEMENTAL INFORMATION E DISCLOSURE STATEMENT		APPLICANT(S): Fitzgerald						
		SERIAL NO.: 10/022,689						
		FILING DATE: December 17, 2001						
		GROUP: 2813						
U.S. PATENT DOCUMENTS								
EXAM. INIT.	DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE IF APPROPRIATE		
FOREIGN PATENT DOCUMENTS								
EXAM. INIT.	DOCUMENT NUMBER	DATE	COUNTRY CODE	CLASS	SUB CLASS	FILING DATE	ABSTRACT ONLY	ENGLISH LANG (Y/N)
OTHER ART, JOURNAL ARTICLES								
EXAM. INIT.	OTHER DOCUMENTS: (Including Author, Title, Date, Relevant Pages, Place of Publication)							
	C97	Halsall <i>et al.</i> , "Electron diffraction and Raman studies of the effect of substrate misorientation on ordering in the AlGaInP system," <i>Journal of Applied Physics</i> , Vol. 85, No. 1 (1999), pp. 199-202.						
	C98	Hsu <i>et al.</i> , "Surface morphology of related Ge ₂ Si ₃ films," <i>Appl. Phys. Lett.</i> , Vol. 61, No. 11 (1992), pp. 1293-1295						
	C99	Huang <i>et al.</i> , (2001) "Carrier Mobility enhancement in strained Si-on-insulator fabricated by wafer bonding", 2001 Symposium on VLSI Technology, Digest of Technical Papers, pages 57-58						
	C100	Langdo <i>et al.</i> , (2002) "Preparation of Novel SiGe-free Strained Si on Insulator Substrates" <i>IEEE International SOI Conference</i> , pages 211-212 (XP002263057)						
EXAMINER				DATE CONSIDERED 3/3/05				